

September 12, 2002
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Revised

List of information/changes needed from Pisa for the Ladder PRR:

1. Details communicated to SLAC on how configuration control is handled for the tooling drawings in Italy. If there is no real configuration control, then we need to get them into the SLAC system asap.
2. If at all possible, please insert into the table 3 the references to all relevant internal documents at G&A. As discussed, this should include the wire-bond visual inspection procedure or standard.
3. Please review the 891 document for clear definitions of the criteria for acceptance. For example, leakage current less than 4uA, depletion voltage less than 120V, no more than 12 bad strips (I just made this up, based on the limit per SSD of 3 strips imposed on HPK).
4. The database should have added to it an entry to identify the procedure and revision number that is actually used in the production of a given ladder.
5. We need to establish a formal schedule for a ladder status report and conformance report to be sent to Sandro and forwarded to Robert. I suggest weekly. I'm sure that Luca can program Access to make a suitable report with very little work needed then each week to generate it and email it.
6. We need to establish and document in 635 a formal schedule for periodic checking of the tooling. I think this could be primarily, or entirely, visual.
7. We need to communicate at the review a definitive plan to test and qualify the new encapsulant. I would include in this some environmental testing, as I mentioned. Although I don't think it would ever happen, I have nightmares of a whole strip of encapsulant coming off with all the wirebonds when thermal cycled and vibrated.